

## News Release

12<sup>th</sup> January 2018

In December 2017, SEMICAPS responded to Hamamatsu's Inter Partes Review filings (IPR2017-02110 and IPR2017-02112) against claims of our US Patent 7,623,982 B2. SEMICAPS has filed a lawsuit in the Northern District of California alleging infringement of claims of this patent in June 2017.

SEMICAPS' case is supported by Dr Michael (Mike) Bruce the foremost expert in the area of static and dynamic laser based localization techniques used in the failure and yield analysis of semiconductors. Mike holds 79 patents. Among these, his Soft Defect Localization technique is acknowledged by a 2015 review in the EDFA magazine as "*perhaps the greatest innovation*" in this area.

In his supporting declaration Dr Bruce noted that the IPR depended heavily upon 2 cited references: Hamada (Japanese Patent Publication 2003-179108) and Quah (DC-Coupled Laser Induced Detection System for Fault Localization in Microelectronic Failure Analysis, Proceedings of the 13<sup>th</sup> IPFA, Singapore 2006, pp. 327-332). However, Mike asserts that neither of these discloses a pulsed laser. Further, he also noted that Hamada does not disclose the key aspect of taking a plurality of samples from a signal response. This aspect is the main limitation in claim 1 of the '982 patent. In addition, Dr Bruce pointed out that Hamada's test signal is dynamic in nature, unlike the static test signal used in the '982 patent. This clearly shows that the 2 systems are fundamentally different in nature.

SEMICAPS continues to believe that it has a strong position in this patent dispute. Documents related to this IPR are publicly available and can be found on the USPTO website. Please go to <https://ptab.uspto.gov/> and search for the IPR using SEMICAPS as your keyword.

## **News Release**

31st October 2017

The patent infringement lawsuit filed by SEMICAPS against Hamamatsu in California has been held in abeyance pending an inter partes review (IPR) filed by Hamamatsu against US Patent 7,623,982. The IPR was filed with the USPTO in September 2017.

SEMICAPS will rigorously defend the IPR action and the company is confident that the relevant claims of the patent that are involved in the patent infringement lawsuit will survive the IPR.

For more details, visit

[https://www.docketalarm.com/cases/PTAB/IPR2017-02110/Inter\\_Parties\\_Review\\_of\\_U.S.\\_Pat.\\_7623982/](https://www.docketalarm.com/cases/PTAB/IPR2017-02110/Inter_Parties_Review_of_U.S._Pat._7623982/)

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## **News Release**

27th June 2017

SEMICAPS Pte Ltd, a wholly owned subsidiary of SEMICAPS Corporation Pte Ltd has filed a patent infringement lawsuit against Hamamatsu Corporation, Photonics Management Corp and Hamamatsu Photonics KK. The court complaint was submitted on 14th June 2017 in the Northern District of California, USA.

SEMICAPS alleges that Hamamatsu's Phemos and iPhemos systems fitted with the M10383 Digital Lock-In Kit or any other similar kit infringes US Patent No. 7,623,982. This digital lock-in technique (together with laser pulsing) improves the sensitivity of OBIRCH and TIVA analysis significantly. Hamamatsu's Lock-In Kit and the use of such a Kit in the Phemos and iPhemos systems allegedly violate SEMICAPS' intellectual property rights.

Licensing negotiation was not fruitful and SEMICAPS was left with no other viable alternative except to seek redress through the law courts. SEMICAPS is represented by David D. Schumann of Marton Ribera Schumann & Chang LLP in San Francisco.

Please see also: <http://norcalrecord.com/stories/511130914-semicaps-pte-ltd-alleges-hamamatsu-kit-infringes-patent>

## **About SEMICAPS**

SEMICAPS is the world's most technologically advanced company in the field of failure localization analysis in semiconductors. Used by leading companies like GlobalFoundries, AMD and Intel for their design-debug and yield analyses, the SEMICAPS laser probe microscope is capable for semiconductor technology nodes as small as 10 nm. Further, besides the standard laboratory configurations, the SEMICAPS Wafer Probing platform, the SEMICAPS 5000, allows semiconductor wafer of complex logic chips to be analysed without the need for sorting, dicing and packaging. This saves weeks for foundries undergoing their yield enhancement cycle.

SEMICAPS, founded in 1988, is a technology spinoff from the National University of Singapore.